

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : **EXPEDITED PROCESSING REQUESTED**
:
AOYAMA, et al. : Art Unit: 2841
:
Serial No: 09/892,630 :
: Examiner: T. Dinh
Filed: June 28, 2001 :
:
For: LEAD-FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL
COMPONENT USING SAID LEAD-FREE SOLDER

AFTER FINAL AMENDMENT UNDER 37 CFR §1.116

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

May 9, 2006

Sir:

This Amendment is filed in response to the final Official Action dated March 14, 2006, the time for response to which is up to and including June 14, 2006.

Please amend the above-identified application as listed below and as set forth on the following pages.

Amendments to the Claims

Remarks are included following the amendments

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-16 (Cancelled)

17. (Previously presented) An alloy composition for a lead free solder for connecting a connection lead to a material, consisting of:

0.002 to 0.015% by mass of phosphorus;

2.0 to 5.0% by mass of silver;

0.01 to 2.0% by mass of copper; and

tin.

18-27 (Cancelled)

28. (Newly presented) A connection lead comprising:

a copper strip or other strip conductor; and

a plating provided on at least one side of the strip conductor;

wherein said plating comprises a lead free solder, and the lead free solder consists of 0.002 to 0.015% by mass of phosphorus, 2.0 to 5.0% by mass of silver, 0.01 to 2.0% by mass of copper, and tin.